



HGB64ON25S , HGP64ON25S HGK64ON25S

P-1

250V N-Ch Power MOSFET

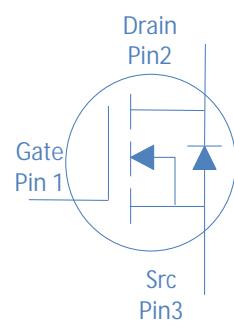
Feature

- High Speed Power Switching
- Enhanced Body diode dv/dt capability
- Enhanced Avalanche Ruggedness
- 100% UIS Tested, 100% Rg Tested
- Lead Free

tion

continuous Rectification in SMPS
Switching and High Speed Circuit

V_{DS}	250	V
$R_{DS(on),typ}$	TO-263	50 mΩ
$R_{DS(on),typ}$	TO-247	50 mΩ
$R_{DS(on),typ}$	TO-220	50 mΩ
I_D	35	A



(unless specified)

Conditions	Value	Unit
	35	A
	25	
	250	V
	± 20	V
	110	A
	112	mJ
	214	W
	-55 to 175	

Terminal Resistor
Normal Resistor

Max	Unit
60	mA

Electrical Characteristics at $T_j=25^\circ\text{C}$ (unless otherwise specified)
Static Characteristics

Parameter	Symbol	Conditions	Value			Unit	
			min	typ	max		
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	250	-	-	V	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\mu\text{A}$	2	3	4		
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=250\text{V}, T_j=25^\circ\text{C}$	-	-	1	μA	
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=250\text{V}, T_j=100^\circ\text{C}$	-	-	100		
Gate to Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	±100	nA	
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=10\text{A}$	TO-263	-	50	64	$\text{m}\Omega$
	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=10\text{A}$	TO-247	-	50	64	$\text{m}\Omega$
	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=10\text{A}$	TO-220	-	50	64	$\text{m}\Omega$
Transconductance	g_{fs}	$V_{\text{DS}}=5\text{V}, I_D=10\text{A}$	-	31	-	S	
Gate Resistance	R_G	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	4.4	-	Ω	

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=100\text{V}, f=1\text{MHz}$	-	1584	-	pF
Output Capacitance	C_{oss}		-	104	-	
Reverse Transfer Capacitance	C_{rss}		-	7.6	-	
Total Gate Charge	Q_g	$V_{\text{DD}}=125\text{V}, I_D=10\text{A}, V_{\text{GS}}=10\text{V}$	-	20	-	nC
Gate to Source Charge	Q_{gs}		-	7	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	3	-	
Turn on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=125\text{V}, I_D=10\text{A}, V_{\text{GS}}=10\text{V}, R_G=10\Omega,$	-	13	-	ns
Rise time	t_r		-	18	-	
Turn off Delay Time	$t_{\text{d(off)}}$		-	25	-	
Fall Time	t_f		-	10	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_F=10\text{A}$	-	0.9	1.2	V
Reverse Recovery Time	t_{rr}	$V_R=125\text{V}, I_F=10\text{A}, dI_F/dt=100\text{A}/\mu\text{s}$	-	110	-	ns
Reverse Recovery Charge	Q_{rr}		-	440	-	nC

Fig 1. Typical Output Characteristics

Figure 2. On-Resistance vs. Gate-Source Voltage

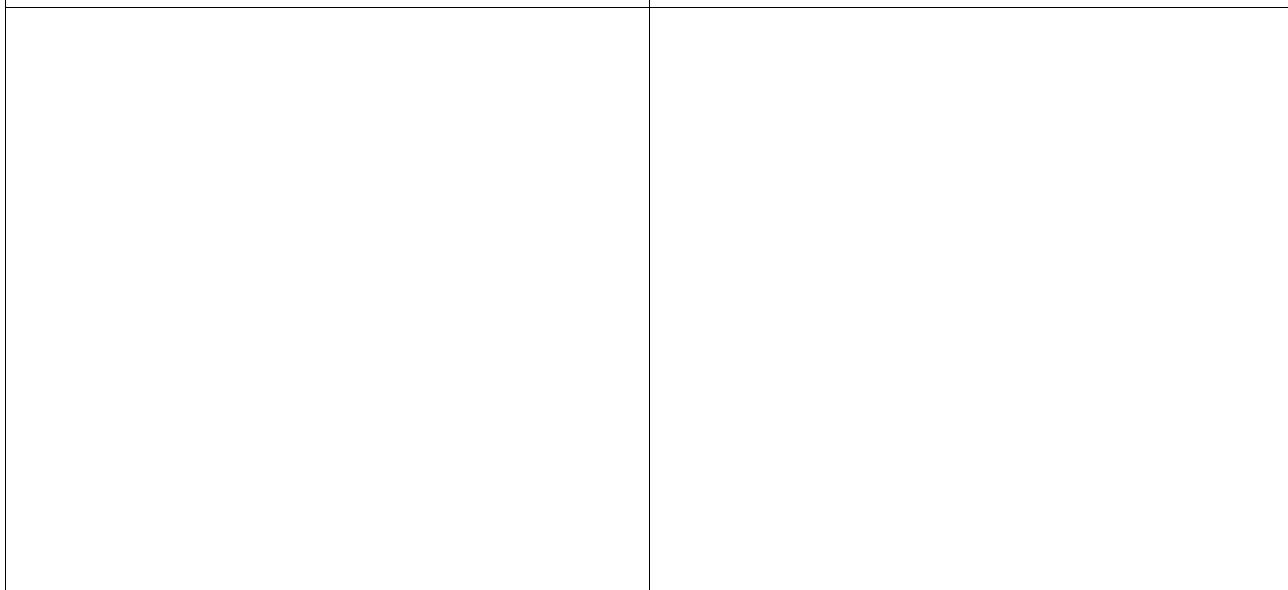


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

Figure 4. Normalized On-Resistance vs. Junction Temperature

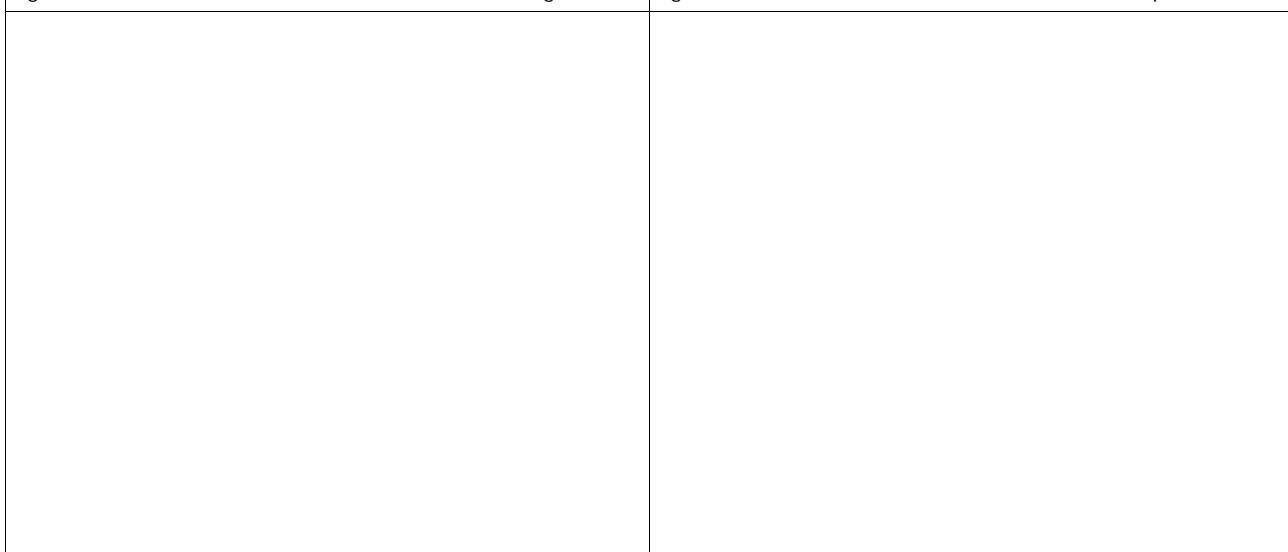


Figure 5. Typical Transfer Characteristics

Figure 6. Typical Source-Drain Diode Forward Voltage

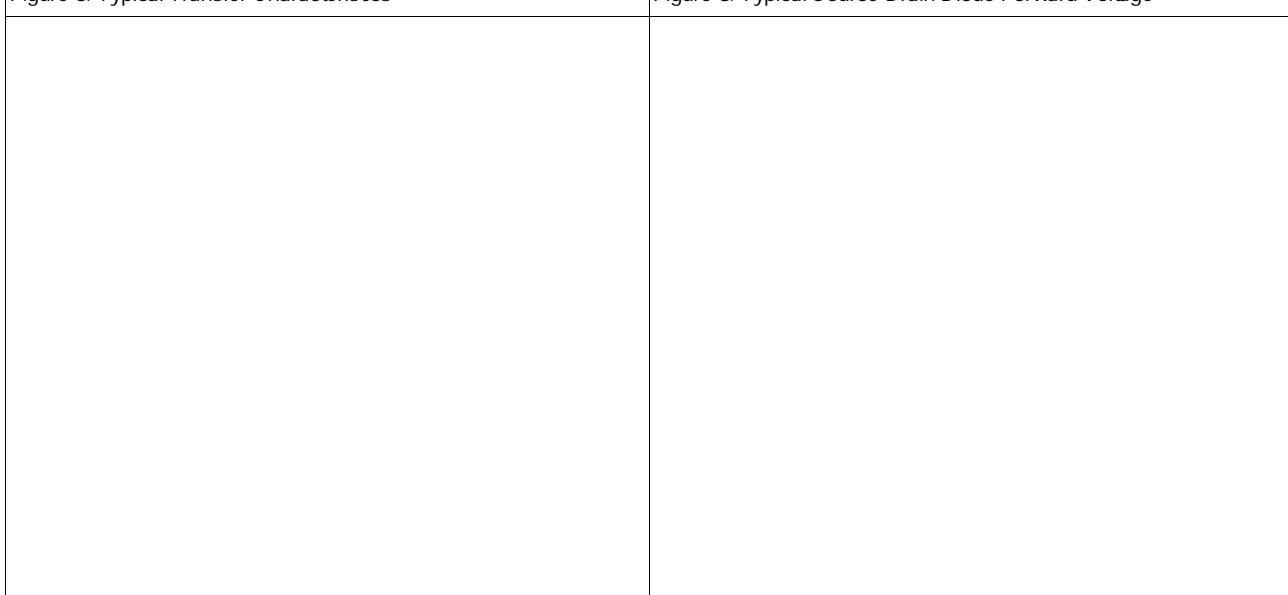


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

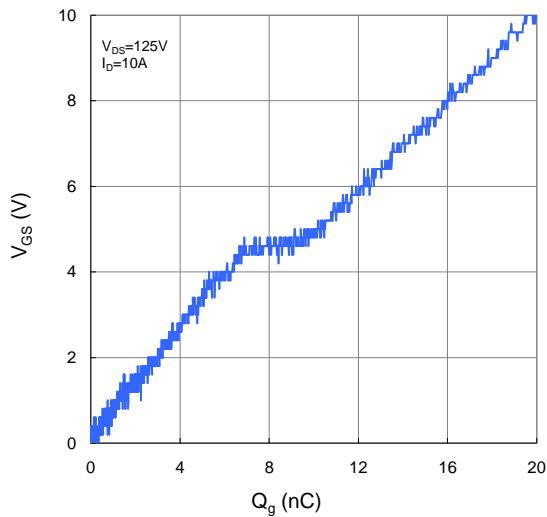


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

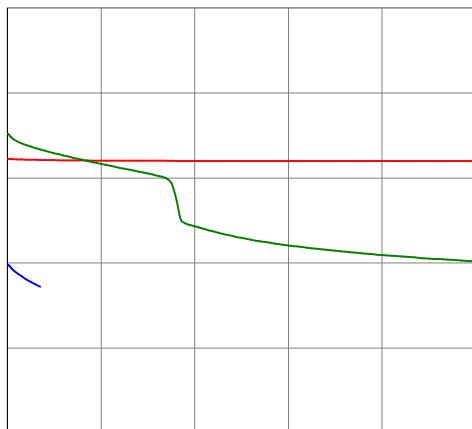


Figure 9. Maximum Safe Operating Area

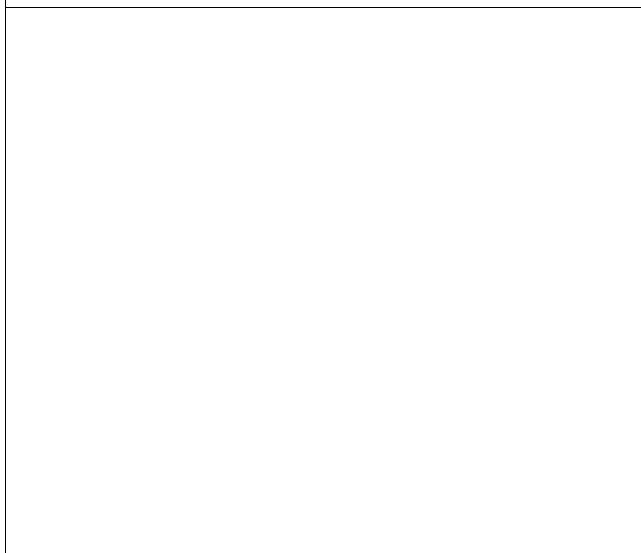


Figure 10. Maximum Drain Current vs. Case Temperature

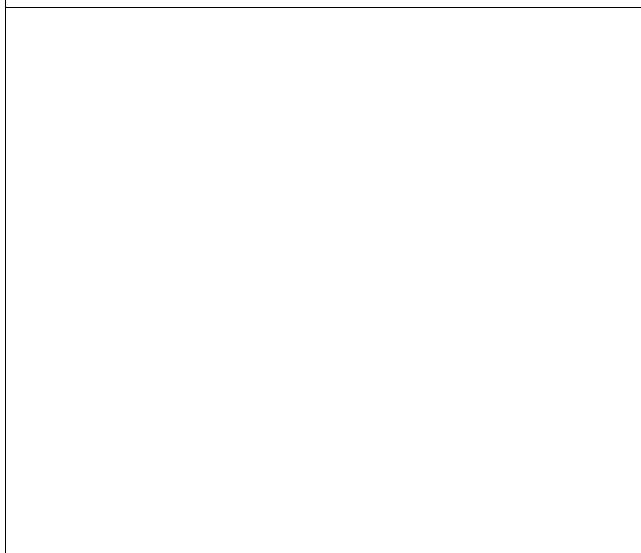
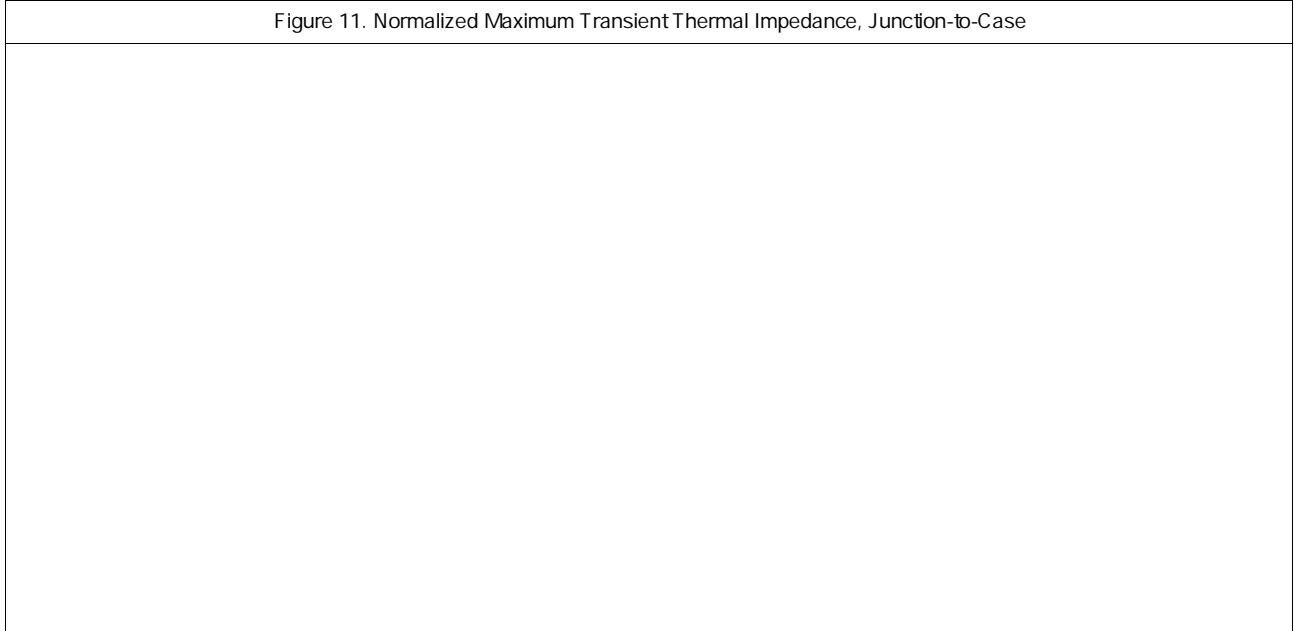


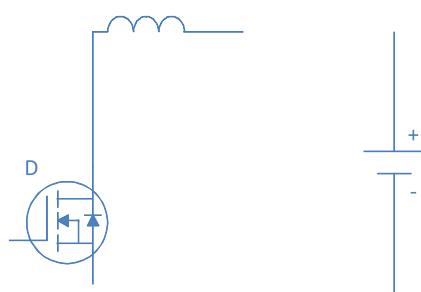
Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case



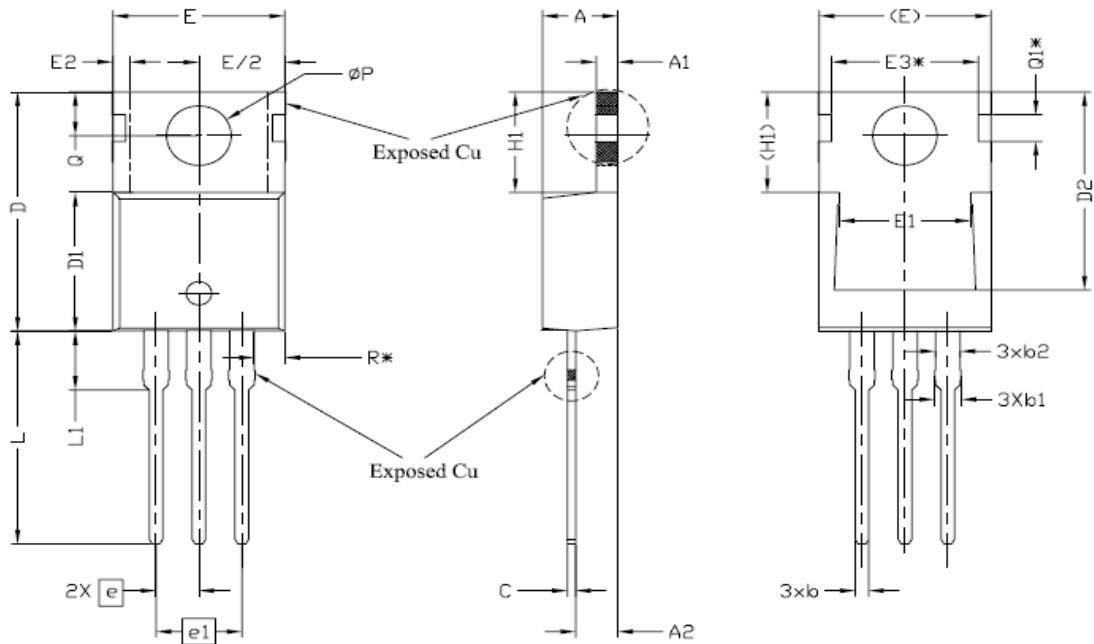
Inductive switching Test

Gate Charge Test

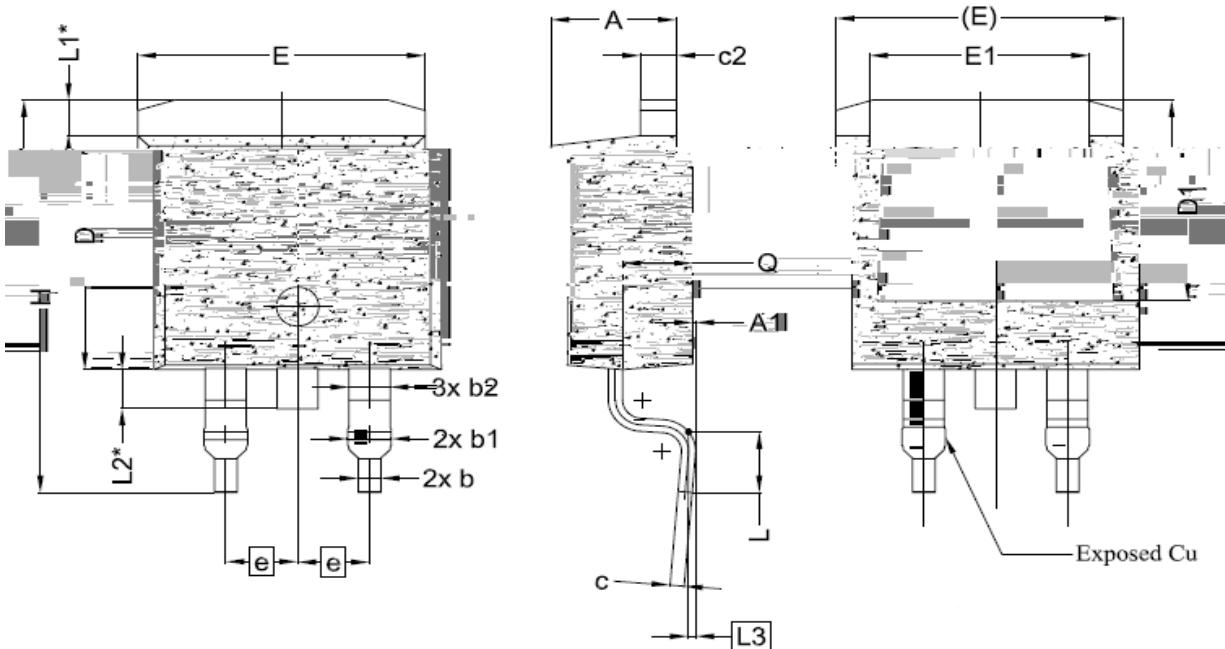
Uclamped Inductive Switching (UIS) Test



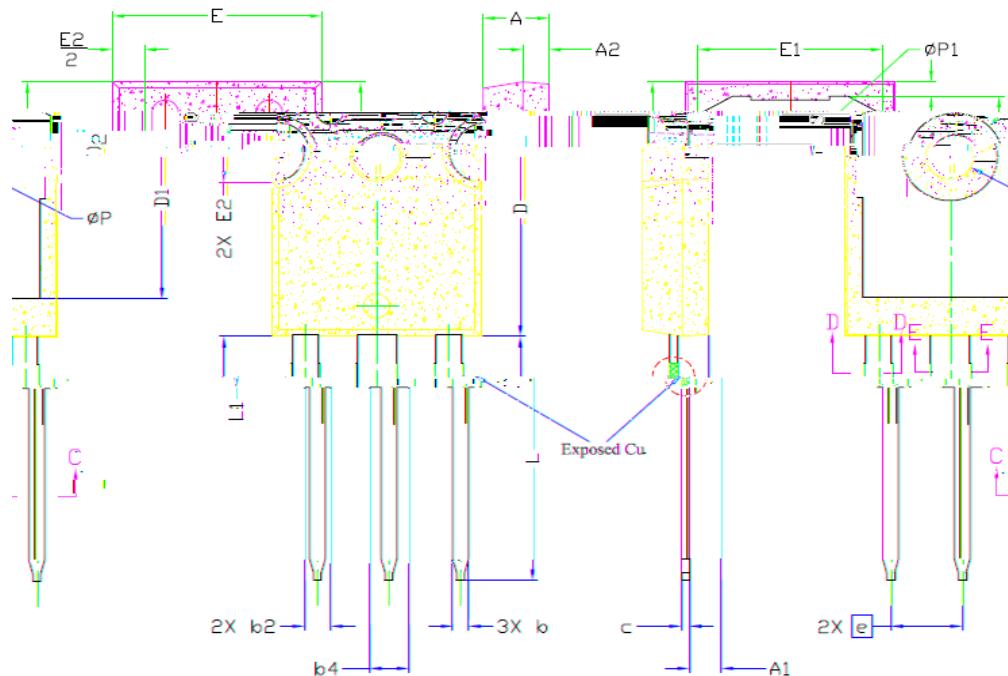
Diode Recovery Test

TO-220, 3 leads


SYMBOL	DIMENSIONS			NOTES
	MIN.	NOM.	MAX.	
A	4,24	4,44	4,64	
A1	1,15	1,27	1,40	
A2	2,30	2,48	2,70	
b	0,70	0,80	0,90	
b1	1,20	1,55	1,75	
b2	1,20	1,45	1,70	
c	0,40	0,50	0,60	
D	14,70	15,37	16,00	4
D1	8,82	8,92	9,02	
D2	12,63	12,73	12,83	5
E	9,96	10,16	10,36	4,5
E1	6,86	7,77	8,89	5
E2	-	-	0,76	6
E3*	8,70REF.			
e	2,54BSC			
e1	5,08BSC			
H1	6,30	6,45	6,60	5,6
L	13,47	13,72	13,97	
L1	3,60	3,80	4,00	
ØP	3,75	3,84	3,93	
Q	2,60	2,80	3,00	
Q1*	1,73REF.			
R*	1,82REF.			

TO-263, 3 leads


SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	4.24	4.44	4.64
A1	0.00	0.10	0.25
b	0.70	0.80	0.90
b1	1.20	1.55	1.75
b2	1.20	1.45	1.70
c	0.40	0.50	0.60
c2	1.15	1.27	1.40
D	8.82	8.92	9.02
D1	6.86	7.65	—
E	9.96	10.16	10.36
E1	6.89	7.77	7.89
e	2.54 BSC		
H	14,61	15,00	15,88
L	1.78	2.32	2.79
L1	1.36 REF.		
L2	1.50 REF.		
L3	0.25 BSC		
Q	2.30	2.48	2.70

TO-247, 3 leads


SYMBOL	DIMENSIONS			NOTES
	MIN.	NOM.	MAX.	
A	4.83	5.02	5.21	
A1	2.29	2.41	2.55	
A2	1.50	2.00	2.49	
b	1.12	1.20	1.33	
b1	1.12	1.20	1.28	
b2	1.91	2.00	2.39	6
b3	1.91	2.00	2.34	
b4	2.87	3.00	3.22	6, 8
b5	2.87	3.00	3.18	
c	0.55	0.60	0.69	6
c1	0.55	0.60	0.65	
D	20.80	20.95	21.10	4
D1	16.25	16.55	17.65	5
D2	0.51	1.19	1.35	
E	15.75	15.94	16.13	4
E1	13.46	14.02	14.16	5
E2	4.32	4.91	5.49	3
e	5.44BSC			
L	19.81	20.07	20.32	
L1	4.10	4.19	4.40	6
ØP	3.56	3.61	3.65	7
ØP1	7.19REF.			
Q	5.39	5.79	6.20	
S	6.04	6.17	6.30	